

REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Changes in accordance with N.O.R. 5962-R043-93.	92-12-23	M. A. FRYE
B	Drawing being updated to reflect current requirements. - ro	00-09-11	R. MONNIN
C	Made changes to replace reference to MIL-STD-973 with reference to MIL-PRF-38535. - ro	03-03-21	R. MONNIN

THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.

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REV STATUS	REV	C	C	C	C	C	C	C	C	C	C	C	C	C	C					
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12							
PMIC N/A	PREPARED BY RICK C. OFFICER		<p align="center">DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216 http://www.dsc.dla.mil</p>																	
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p align="center">AMSC N/A</p>	CHECKED BY SANDRA ROONEY																			
	APPROVED BY MICHAEL A. FRYE		<p align="center">MICROCIRCUIT, LINEAR, PRECISION FAST SETTLING, OPERATIONAL AMPLIFIER, MONOLITHIC SILICON</p>																	
	DRAWING APPROVAL DATE 92-05-21																			
	REVISION LEVEL C		SIZE A	CAGE CODE 67268	5962-90980															
		SHEET 1 OF 12																		

1.3 Absolute maximum ratings. 1/ 2/

Voltage between +V _S and -V _S terminals	36 V dc
Differential input voltage	±6.0 V dc
Voltage at either input terminal	+V _S to -V _S
Peak output current (< 10 % duty cycle)	100 mA
Power dissipation (P _D):	
Case P	1.3 W 3/
Case X	1.5 W 3/
Case 2	1.0 W 3/
Junction temperature (T _J)	+175°C
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case (θ _{JC}):	
Case P	22°C/W
Case X	65°C/W
Case 2	35°C/W
Thermal resistance, junction-to-ambient (θ _{JA}):	
Case P	110°C/W
Case X	80°C/W
Case 2	150°C/W

1.4 Recommended operating conditions.

Positive supply voltage range (+V _S)	+4.5 V dc to +15 V dc
Negative supply voltage range (-V _S)	-4.5 V dc to -15 V dc
Common mode input voltage (V _{CM})	±10 V
Load resistance (R _L)	500 Ω
Ambient temperature range (T _A)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

- 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- 2/ Unless otherwise specified, T_A = +25°C.
- 3/ Derate linearly above T_A = +25°C for case P at 8.7 mW/°C, case X at 10 mW/°C, and case 2 at 6.7 mW/°C.

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HANDBOOKS

DEPARTMENT OF DEFENSE

- MIL-HDBK-103 - List of Standard Microcircuit Drawings.
- MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.3 Electrical performance characteristics and post irradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and post irradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-PRF-38535, appendix A.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _A ≤ +125°C ±V _S = ±15 V unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Input offset voltage	V _{IO}	V _{CM} = 0 V	1	01	-2.0	+2.0	mV
			2,3		-4.5	+4.5	
Input bias current	I _B	V _{CM} = 0 V	1	01		2.5	nA
			2,3 <u>3/</u>			2600	
Input offset current	I _{IO}	V _{CM} = 0 V	1	01	-1	+1	nA
			2,3 <u>3/</u>		-1025	+1025	
Common mode voltage range	+V _{CM}	+V _S = 5.0 V, -V _S = -25 V, V _{OUT} = -10 V	1,2,3	01	10		V
	-V _{CM}	+V _S = 25 V, -V _S = -5.0 V, V _{OUT} = 10 V				-10	
Large signal voltage gain	+A _{VOL}	V _{OUT} = 0 V and 10 V, R _L = 500 Ω	1	01	15		V/mV
			2,3		10		
	-A _{VOL}	V _{OUT} = 0 V and -10 V, R _L = 500 Ω	1	15			
			2,3	10			
Quiescent power <u>4/</u> consumption	P _C	V _{OUT} = 0 V, I _{OUT} = 0 mA	1	01		390	mW
			2,3			480	
Output current	+I _{OUT}	V _{OUT} = 0 V, T _A = +25°C	1	01	50		mA
	-I _{OUT}					-50	
Output voltage swing	+V _{OUT}	R _L = 500 Ω	1,2,3	01	10		V
	-V _{OUT}					-10	
Quiescent power supply current	I _{CC}	V _{OUT} = 0 V, I _{OUT} = 0 mA	1	01		13	mA
			2,3			16	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _A ≤ +125°C ±V _S = ±15 V unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Power supply rejection ratio	+PSRR	+V _S = 5.0 V to 18 V, -V _S = -15 V	1	01	65		dB
			2,3		62		
	-PSRR	-V _S = -5.0 V to -18 V, +V _S = +15 V	1		65		
			2,3		62		
Common mode rejection ratio	+CMRR	ΔV _{CM} = 10 V, +V _S = 5.0 V, -V _S = -25 V, V _{OUT} = -10 V	4,5,6	01	60		dB
	-CMRR	ΔV _{CM} = -10 V, +V _S = 25.0 V, -V _S = -5.0 V, V _{OUT} = 10 V			60		
Gain bandwidth product <u>3/</u>	GBWP	V _{OUT} = ±100 mV, R _L = 500 Ω, f ₁ = 100 kHz, f ₂ = 10 MHz, T _A = +25°C	4	01	20		MHz
Full power bandwidth <u>3/ 5/</u>	FPBW	V _{PK} = 10 V, R _L = 500 Ω, T _A = +25°C	4	01	2.3		MHz
Closed loop stable <u>3/</u> gain	CLSG	R _L = 500 Ω, C _L ≤ 10 pF	4,5,6	01	1		V/V
Slew rate <u>3/</u>	+SR	V _{OUT} = -5.0 V to +5.0 V, R _L = 500 Ω, A _V = -1 V/V, measured at -5 V to +5 V	4	01	200		V/μs
			5,6		160		
	-SR	V _{OUT} = +5.0 V to -5.0 V, R _L = 500 Ω, A _V = -1 V/V, measured at +5 V to -5 V	4		200		
			5,6		160		
Rise time <u>3/ 6/</u>	t _R	V _{OUT} = 0 V to +200 mV, A _V = +1, R _L = 500 Ω	9,10,11	01		11	ns
Fall time <u>3/ 6/</u>	t _F	V _{OUT} = 0 V to -200 mV, A _V = +1, R _L = 500 Ω	9,10,11	01		11	ns

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _A ≤ +125°C ±V _S = ±15 V unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Settling time <u>3/</u>	t _S	A _V = -1 V/V, R _L = 500 Ω, 10 V step at 0.1 % of the final value, T _A = +25°C	9	01		160	ns
		A _V = -1 V/V, R _L = 500 Ω, 10 V step at 0.01 % of the final value, T _A = +25°C				250	
Overshoot <u>3/</u>	+OS	V _{OUT} = 0 V to +200 mV, A _V = +1, R _L = 500 Ω, T _A = +25°C	9	01		50	%
	-OS	V _{OUT} = 0 V to -200 mV, A _V = +1, R _L = 500 Ω, T _A = +25°C				50	

1/ Unless otherwise specified, for dc tests, R_L = 100 kΩ, V_{OUT} = 0 V, and all other specifications are guaranteed after the equivalent of five minutes of operation at T_A = +25°C.

2/ The algebraic convention, whereby the most negative is a minimum and the most positive is a maximum, is used in this table. Negative current shall be defined as conventional current flow out of a device terminal.

3/ If not tested, shall be guaranteed to the limits specified in table I herein.

4/ Quiescent power consumption is based on quiescent supply current test maximum with no load on outputs

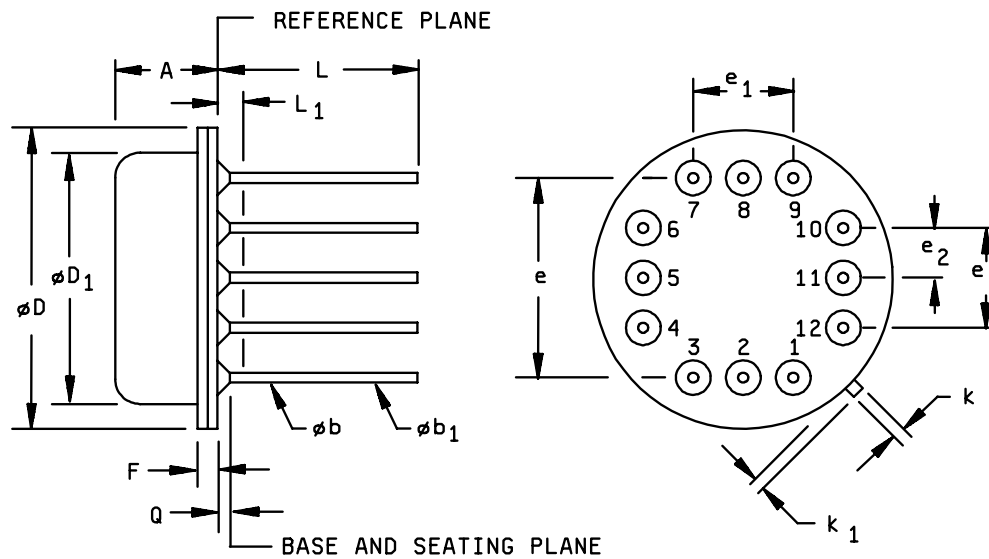
5/ Full power bandwidth = SR / (2 × π × V_{PK}).

6/ Rise and fall times measured between 10 percent and 90 percent point.

3.9 Verification and review for device class M. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 85 (see MIL-PRF-38535, appendix A).

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Symbol	Inches		Millimeters		Notes
	Min	Max	Min	Max	
A	0.148	0.181	3.76	4.60	
ϕb	0.016	0.019	0.41	0.48	1
ϕb_1	0.016	0.021	0.41	0.53	1
ϕD	0.592	0.615	15.04	15.62	
ϕD_1	0.545	0.555	13.84	14.10	
e	0.400 BSC		10.16 BSC		3
e1	0.200 BSC		5.00 BSC		3
e2	0.100 BSC		2.54 BSC		3
F	---	0.400	---	1.02	
k	0.026	0.036	0.66	0.91	
k1	0.027	0.037	0.68	0.94	2
L	0.375	---	9.50	---	
L1	---	0.050	---	1.27	1
Q	0.010	0.045	0.25	1.14	

NOTES:

1. (All leads) ϕb applies between L and L_1 , ϕb_1 applies between L_1 and 0.375 inch (9.50 mm) from the reference plane. Diameter is uncontrolled in L_1 and beyond 0.375 inch (9.50 mm) from the reference plane.
2. Measured from the maximum diameter of the product.
3. Leads having a maximum diameter 0.019 inch (0.48 mm) measured in gauging plane 0.054 inch (1.37 mm) + 0.001 inch (0.03 mm) – 0.000 inch (0.000 mm) below the base plane of the product are within 0.007 inch (0.18 mm) of their true position relative to the maximum width tab.

FIGURE 1. Case outline X.

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Device type	01		
Case outlines	P	X	2
Terminal number	Terminal symbol		
1	BALANCE	NC	NC
2	-INPUT	NC	BALANCE
3	+INPUT	BALANCE	NC
4	-V _S	BALANCE	NC
5	NC	-INPUT	-INPUT
6	OUTPUT	+INPUT	NC
7	+V _S	NC	+INPUT
8	BALANCE	NC	NC
9	---	NC	NC
10	---	-V _S	-V _S
11	---	OUTPUT	NC
12	---	+V _S	NC
13	---	---	NC
14	---	---	NC
15	---	---	OUTPUT
16	---	---	NC
17	---	---	+V _S
18	---	---	NC
19	---	---	NC
20	---	---	BALANCE

NC = No connection

FIGURE 2. Terminal connections.

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4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.

- b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1,2,3,4,9 <u>1/</u>	1,2,3,4,9 <u>1/</u>	1,2,3,4,9 <u>1/</u>
Group A test requirements (see 4.4)	1,2,3,4,5, <u>2/</u> 6,9,10,11	1,2,3,4,5, <u>2/</u> 6,9,10,11	1,2,3,4,5, <u>2/</u> 6,9,10,11
Group C end-point electrical parameters (see 4.4)	1	1	1
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	1	1	1

1/ PDA applies to subgroup 1.

2/ Subgroups 9, 10, and 11, shall be measured only for initial test and after process or design changes and shall be guaranteed to the limits specified in table I herein.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
- b. $T_A = +125^{\circ}\text{C}$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

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4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the post irradiation end-point electrical parameter limits as defined in table I at $T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$, after exposure, to the subgroups specified in table II herein.
- c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.4 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0547.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 03-03-21

Approved sources of supply for SMD 5962-90980 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN 1/	Vendor CAGE number	Vendor similar PIN 2/
5962-9098001MPA	24355	AD843SQ/883B
5962-9098001MXA	24355	AD843SH/883B
5962-9098001M2A	24355	AD843SE/883B

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

24355

Vendor name and address

Analog Devices
Route 1 Industrial Park
P.O. Box 9106
Norwood, MA 02062
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